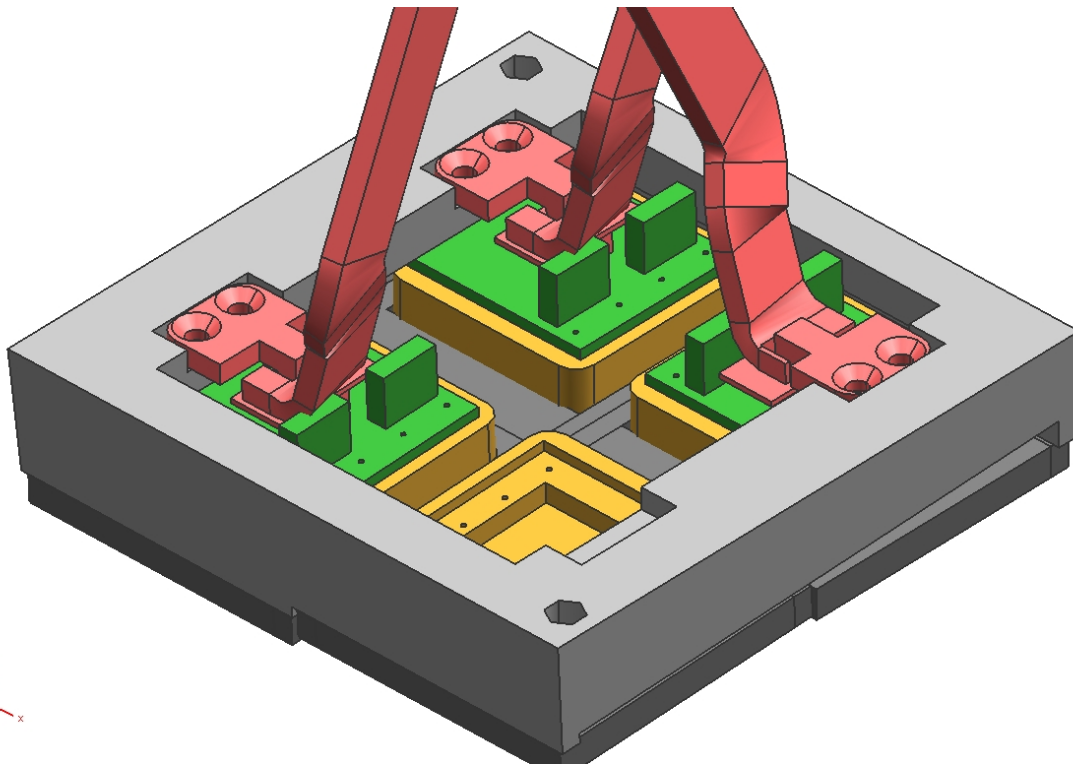


EMC Electronics Developments at KVI

**M. Kavatsyuk, E. Guliyev, P.J.J. Lemmens,
H. Löhner, T.P. Poelman, G. Tambave**

- ASIC board design
- Flexible flat cable for the EMC endcap
- SADC requirements

Insert mounted
with ASIC boards
(old design)



Questions to be answered:

(as for December 2008):

- possibility to fit ASIC with required components on the 18x19 mm² PCB
- dimensions and type of decoupling capacitors
- connection between ASIC board and collector board

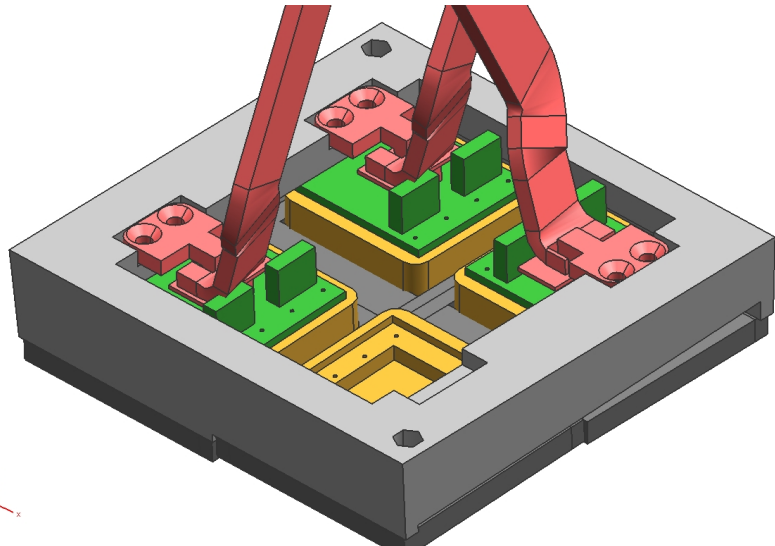
- measurements with $C = \{300\text{n}, 200\text{n}, 100\text{n}, 56\text{n}, 22\text{n}, 7\text{n}, 1.3\text{n}\}$
- data taken with 100MHz 16bit SADC
- traces analysed to deduce:
 - noise level → constant for all values of C
 - the peak integral → constant (deviation $< 0.5\%$) for $C \in \{300\text{n}, 200\text{n}, 100\text{n}, 56\text{n}, 22\text{n}\}$;
for $C = 7\text{n}$ signal drop **2%**
for $C = 1.3\text{n}$ signal drop **10%**

Conclusions: use $C = 56\text{n}$

- type: SMD, X7R dielectric, $V_{\text{max}} = 630\text{V}$
- dimensions: $4.5 \times 3.2 \text{ mm}^2$, height 2.54mm

This choice allows to:

- place capacitors on the same PCB side as ASIC (bottom side)
- rotate LAAPD capsule
- make output on the opposite side to the LAAPD pins



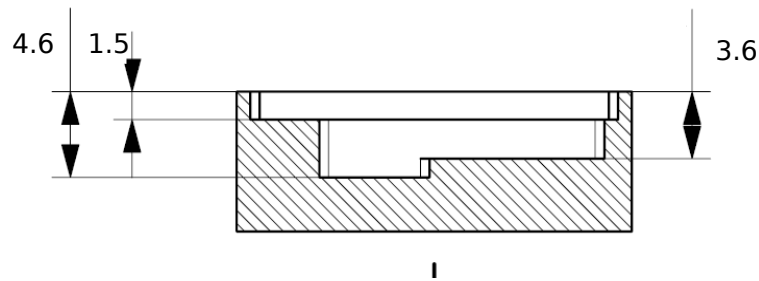
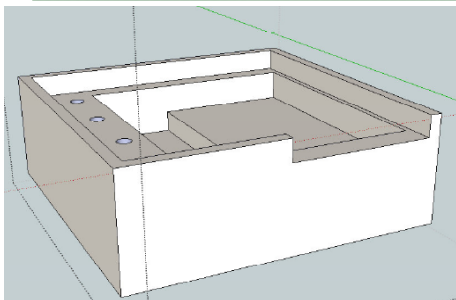
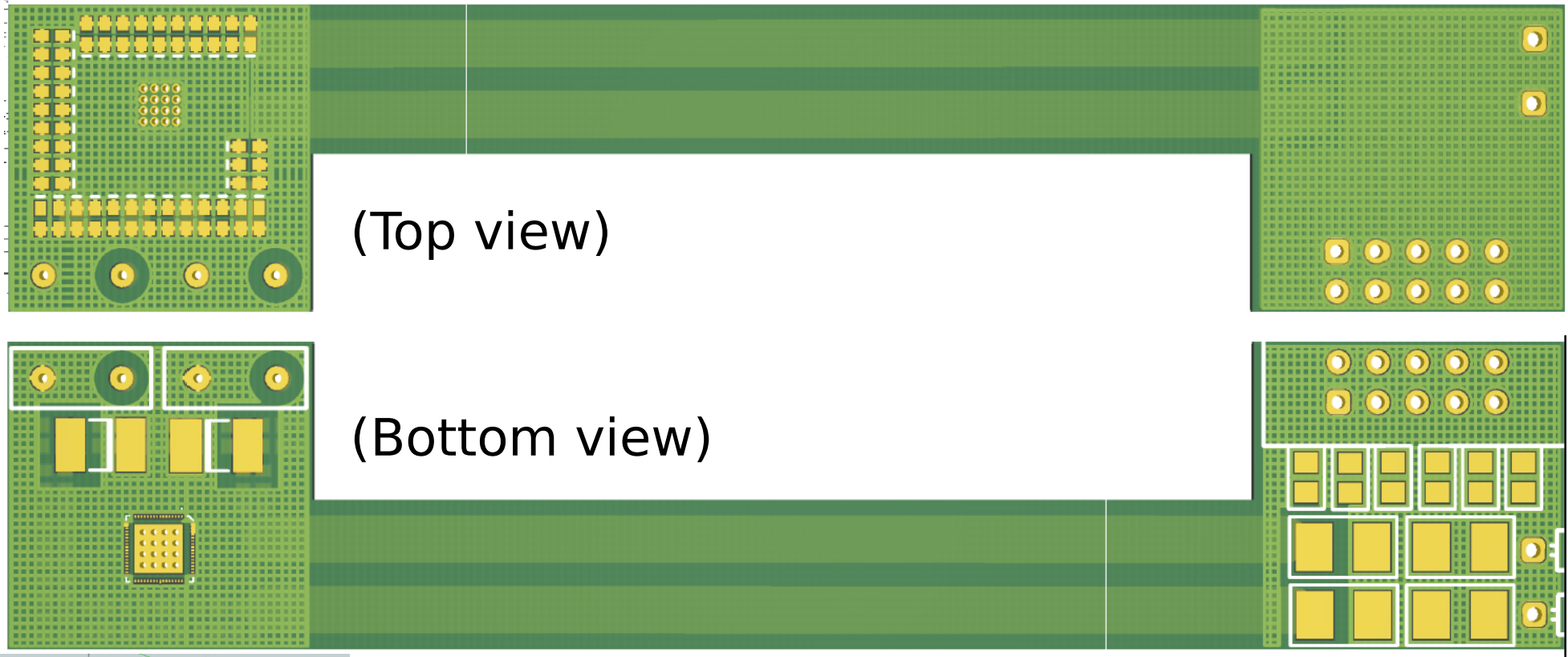
ASIC

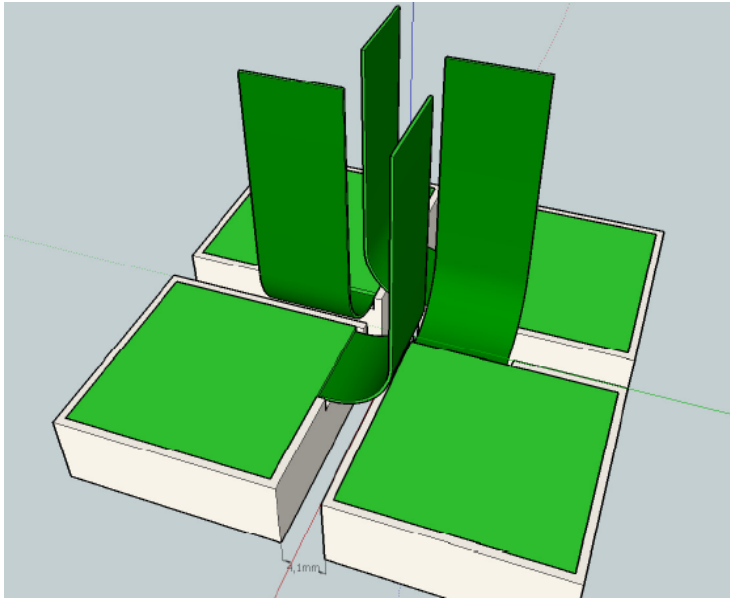
rigid PCB
(8 layers)

Flexible flat cable
(~10cm long; 6 layers)

Connector board

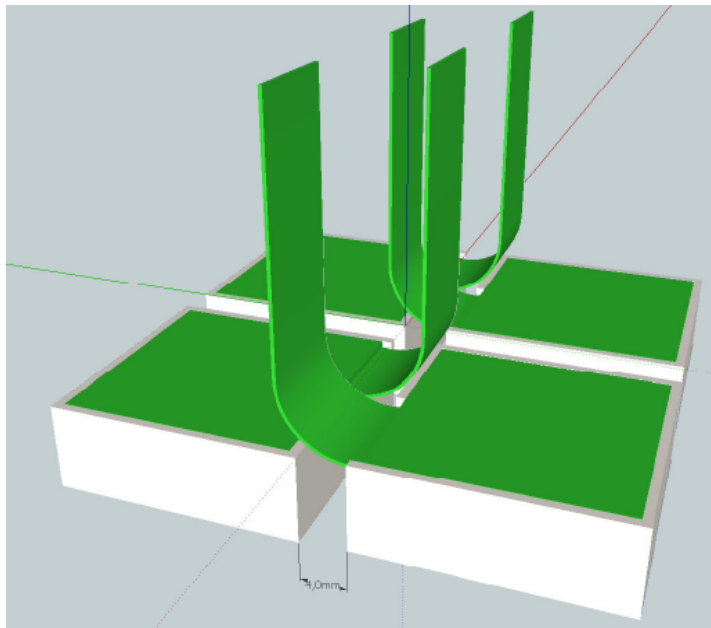
rigid PCB (8 layers)
(HV filter)





Option A

- Requires smaller feed-through for the cables in the supporting plate



Option B

- Requires larger feed-through for the cables in the supporting plate
- Larger bending radius of flexible cables

- The decoupling capacitors are selected (56n, 630V)
- Decoupling capacitors are placed on the same side as ASIC
- The design of ASIC board is almost finished
- The performance can be tested only with prototypes (~end of summer)
- The arrangement of the output cables (options A, B) should be selected according to the mechanical design preferences

- ASIC board design
- Flexible flat cable for the EMC endcap
- SADC requirements

- Investigations are done with prototype rigid PCB
- Achievable cross-talk $\sim 1:62000$ (30 cm long cable)
- Next weeks the complete measurements with prototype will be done



Realistic estimation for the copper budget
(16 channels signals and HV)

- ASIC board design
- Flexible flat cable for the EMC endcap
- SADC requirements

Measurements with LNP preamplifier (100MHz 16bit SADC):

- LED light pulser ($E_{\text{dep}} \sim 180\text{MeV}$): **0.5ns**
- Ion beam (${}^6\text{Li}$ 2AGeV, $E_{\text{dep}} \sim 180\text{MeV}$): **1.2ns**
- High-energy γ -rays ($E_{\text{dep}} \sim 100\text{MeV}$): **1.4ns**

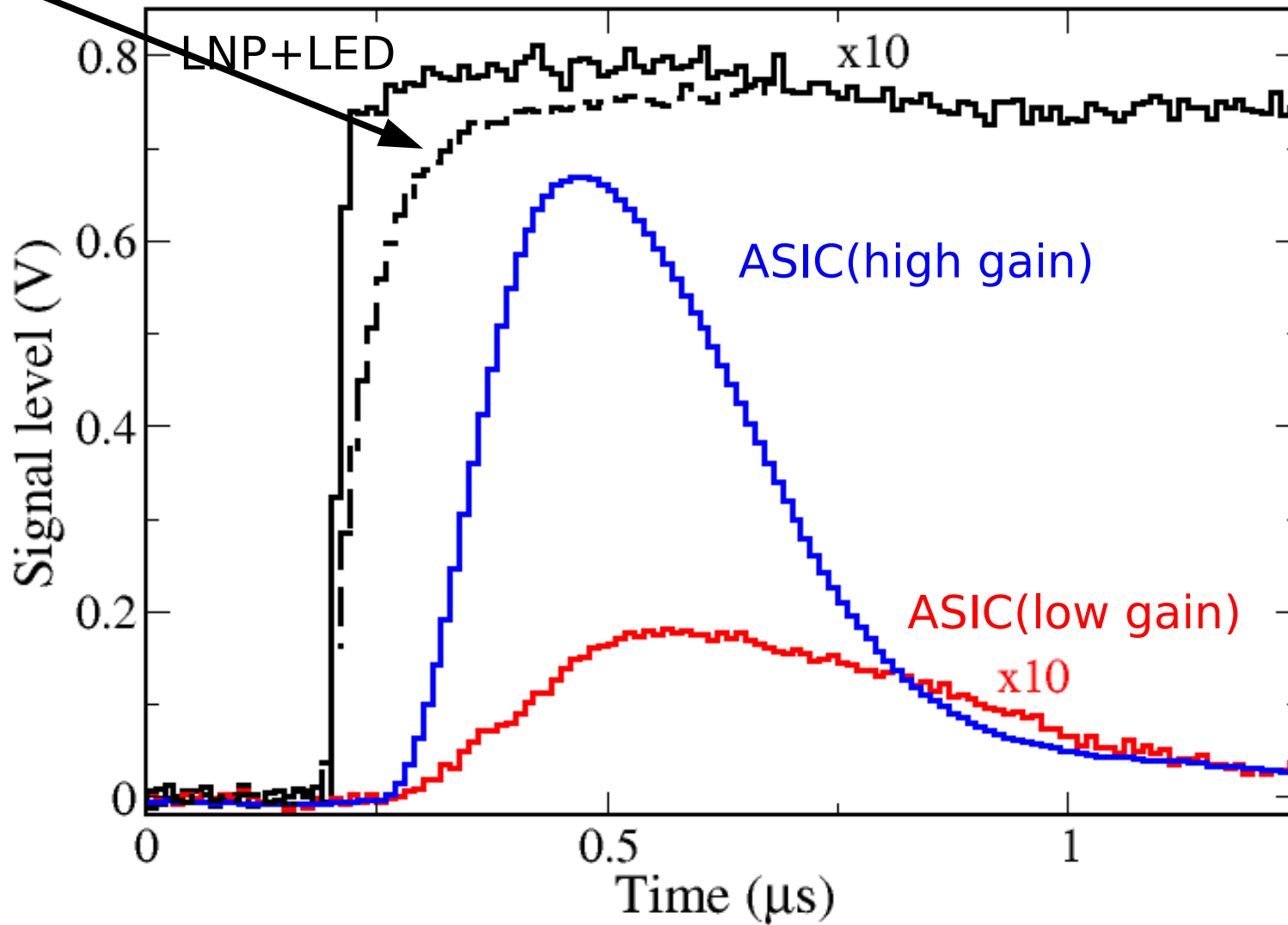
Same results are achieved with sampling rates of **50MHz**
and 25 MHz

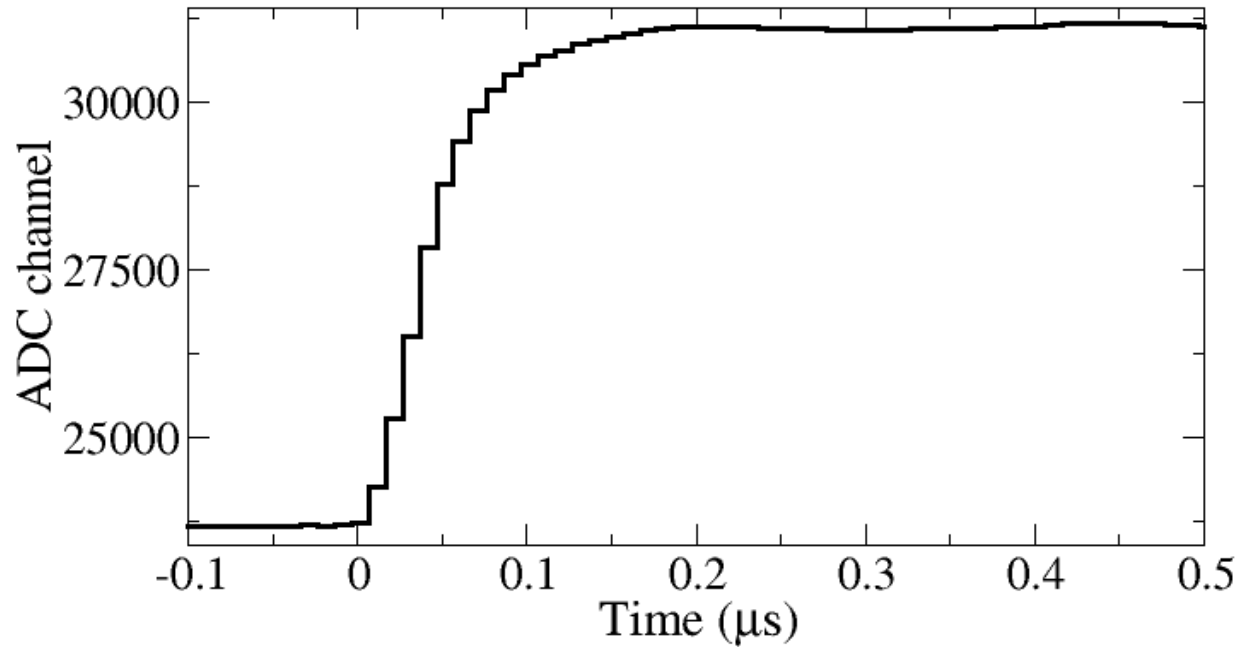
but

results at 25MHz are too sensitive to chosen parameters

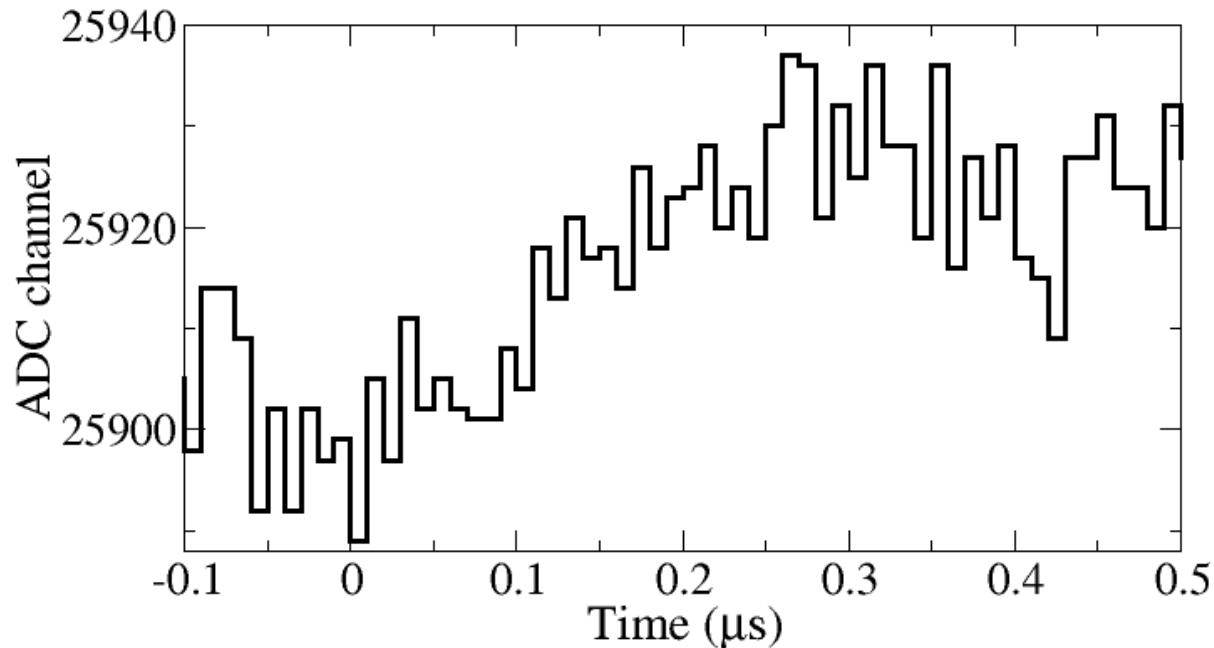
LNP + cosmic rays

One time bin corresponds to 10ns





$E_{\text{dep}} \sim 1 \text{ GeV}$ (gamma)



$E_{\text{dep}} \sim 4 \text{ MeV}$ (cosmic ray)

One time bin
corresponds to 10ns

- Time resolution is limited by the rise time of the signal (1.2ns for $E_{\text{dep}} \sim 180\text{MeV}$)
- Sampling rate of **50 MHz** is sufficient to obtain optimal time and energy resolution
- Two 12bit or one 14bit SADC per LAAPD should be used. At present 12bit SADC are preferable.
Typical effective ASDC resolution:
 - 12 bit \rightarrow 11.5 effective bits
 - 14 bit \rightarrow 12.5 effective bits

To test “real” performance of SADC readout one has to build realistic prototype.

VHDL implementation of the developed feature-extraction algorithms should be tested with measurements

